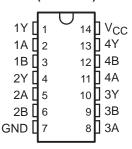
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- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of Up To -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- 2-V to 6-V V_{CC} Operation

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}
- Typical t_{pd} = 8 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

D OR PW PACKAGE (TOP VIEW)



description/ordering information

The SN74HC02 contains four independent 2-input NOR gates. It performs the Boolean function $Y = \overline{A} + \overline{B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACKAC	GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – PW	Tape and reel	SN74HC02QPWREP	SHC02EP
−55°C to 125°C	SOIC - D	Tape and reel	SN74HC02MDREP	HC02MEP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Χ	L
X	Н	L
L	L	Н

logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	$-0.5\ V$ to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2):D package	
PW package	
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	V	
		V _{CC} = 2 V	1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			V	
		V _{CC} = 6 V	4.2				
		V _{CC} = 2 V			0.5		
٧ _{IL}	00				1.35	V	
		V _{CC} = 6 V			1.8		
٧ _I	Input voltage		0		VCC	V	
VO	Output voltage		0		VCC	V	
		V _{CC} = 2 V			1000		
Δt/Δν	Input transition rise/fall time	$V_{CC} = 4.5 \text{ V}$	500		500	ns	
		V _{CC} = 6 V			400		
т.	Operating free air temperature	Q-suffix device	-40		125	°C	
TA	Operating free-air temperature	M-suffix device	-55		125	30	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN74HC02-EP QUADRUPLE 2-INPUT POSITIVE-NOR GATE

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	TEST SOUDITIES	TEST CONDITIONS		Т	A = 25°C	;			
PARAMETER	TEST CONDITIO	DNS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		
			2 V		0.002	0.1		0.1	
		$I_{OL} = 20 \mu\text{A}$	4.5 V		0.001	0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4	
lį	VI = VCC or 0		6 V		±0.1	±100	·	±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			2	·	40	μΑ
Ci			2 V to 6 V		3	10	·	10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

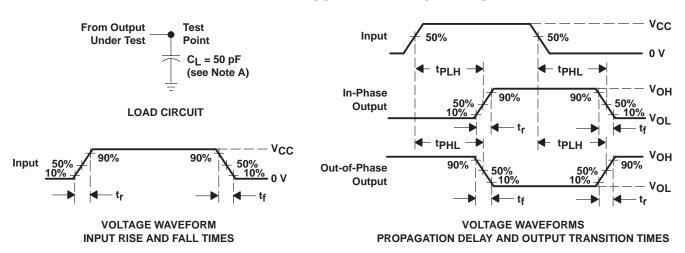
DADAMETED	FROM	то	\ \	T,	λ = 25°C	;	NAIN!	MAV	LINUT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	UNIT
			2 V		45	90		135	
t _{pd}	A or B	Υ	4.5 V		9	18		27	ns
·			6 V		8	15		23	ns
			2 V		38	75		110	
t _t		Υ	4.5 V		8	15		22	ns
			6 V		6	13		19	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	22	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_\Gamma = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC02QPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SHC02EP	Samples
V62/04687-02YE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SHC02EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74HC02-EP:

Catalog: SN74HC02

Automotive: SN74HC02-Q1

• Military: SN54HC02

NOTE: Qualified Version Definitions:

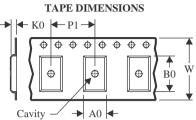
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width						
В0	Dimension designed to accommodate the component length						
K0	Dimension designed to accommodate the component thickness						
W	Overall width of the carrier tape						
P1	Pitch between successive cavity centers						

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC02QPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC02QPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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